## Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

## Listing of Claims

1. (Currently Amended) A method for measuring an unfilled [[a]] patterned structure (3), the pattern comprising features each having a width dimension, the method comprising:

exciting irradiating the <u>unfilled patterned</u> structure (3) by irradiating it with a spatially periodic laser intensity pattern in order to <u>generate excite</u> surface acoustic waves <u>having a</u> wavelength larger than the feature width dimensions:

diffracting a probe laser beam (6) off the thermal grating generated surface acoustic waves to form a signal beam;

detecting the signal beam as a function of time to generate a signal waveform; [[and]]

determining a surface acoustic wave phase velocity from the signal waveform; and

determining at least one property of the patterned structure based on the effect of the
surface profile of the unfilled patterned structure on the surface acoustic wave phase velocity.

- (Original) The method of Claim 1, wherein the exciting step further comprises a spatially periodic laser intensity pattern having a period ranging from 1 to 20 microns.
- (Currently Amended) The method of Claim [[1]] 17, wherein the unfilled patterned structure is comprised of comprises trenches equal to or less than approximately 2 μm in width.
- (Currently Amended) The method of Claim 3, wherein the <u>unfilled</u> patterned structure further comprises a periodic array of trenches.
- (Currently Amended) The method of Claim 4, wherein the <u>unfilled</u> patterned structure further comprises a periodic array of linear trenches.

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- (Currently Amended) The method of Claim 4, wherein the <u>unfilled</u> patterned structure further comprises a two-dimensional periodic array of trenches.
- (Original) The method of Claim 4, wherein the trenches are fabricated in a silicon substrate
- 8. (Original) The method of Claim 3, wherein the trenches are fabricated in a thin film.
- (Currently Amended) The method of Claim [[1]]17, wherein the at least one property
  comprises trench depth.
- (Currently Amended) The method of Claim [[1]]17, wherein the at least one property
  comprises trench width.
- 11. (Original) The method of Claim 1, wherein the at least one property comprises a depth profile of the trench structure.
- 12. (Currently Amended) The method of Claim I, wherein the determining step further comprises combining measurements at multiple acoustic wavelengths to determine multiple parameters of the treneh unfilled patterned structure.
- 13. (Original) The method of Claim 5, wherein the determining step further comprises combining measurements along and across the trench structure to determine both trench depth and width
- 14. (Currently Amended) The method of Claim 1, wherein the determining step further comprises combining measurements within and outside the <u>unfilled</u> patterned area to separate the effect on the surface acoustic wave velocity caused by the <del>trench structure</del> <u>surface profile</u> from other effects such as film thickness.

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- 15. (Currently Amended) The method of claim I, wherein the determining step eomprises analysis of the signal waveform with employs a theoretical model based on effective elastic properties of the structure.
- (Currently Amended) The method of Claim 1, wherein the determining step eomprises
  analysis of the signal waveform with employs a model based on an empirical calibration.
- 17. (New) The method of Claim 1, wherein the unfilled patterned structure comprises a plurality of unfilled trenches.